

Desmear/Electroless Copper for Semi Additive Process

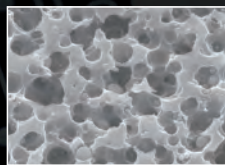
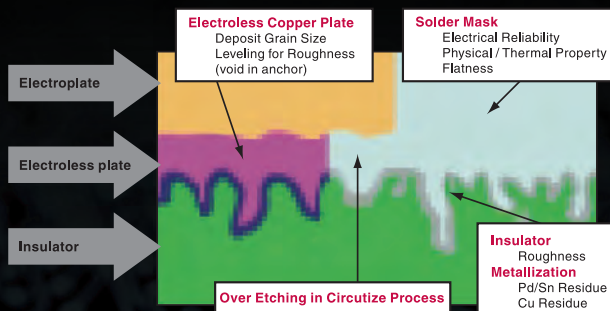
除胶渣及化学沉 铜技术应用于半 加成工艺

CIRCUPOSIT™ 7800 Electroless Copper

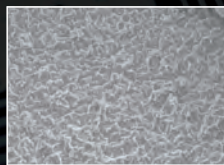
Features and Benefits 特长及优点

- Uniform and stable adhesion promotion treatment and reliable via bottom cleaning
能提升均匀且稳定的表面结合能力及对于盲孔孔底有可靠的清洁能力
- Stable and wide process window
操作范围大且表现稳定
- High peel strength and optimum surface roughness for resist adhesion
抗拉扯强度高，对于乾膜的贴合表面有最理想的粗糙度
- Excellent plating coverage on insulator and via
优越的绝缘层表面及孔内镀层覆盖能力
- Excellent electrical reliability with high insulation resistance
在高度的绝缘阻抗能力下能表现出卓越的信赖性

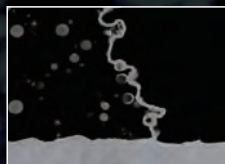
Key Issue for SAP



Adhesion promotion
on insulator



Via Bottom Cleaning

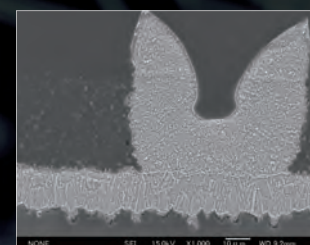
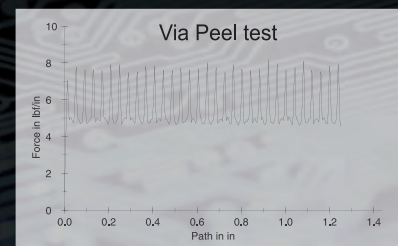
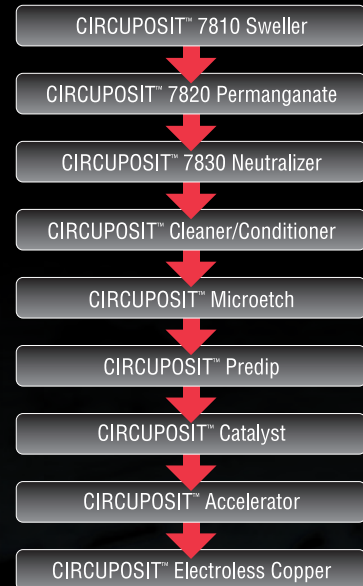


Excellent Plating coverage



Cu-Cu Connection

Process 製程



Electronic Materials